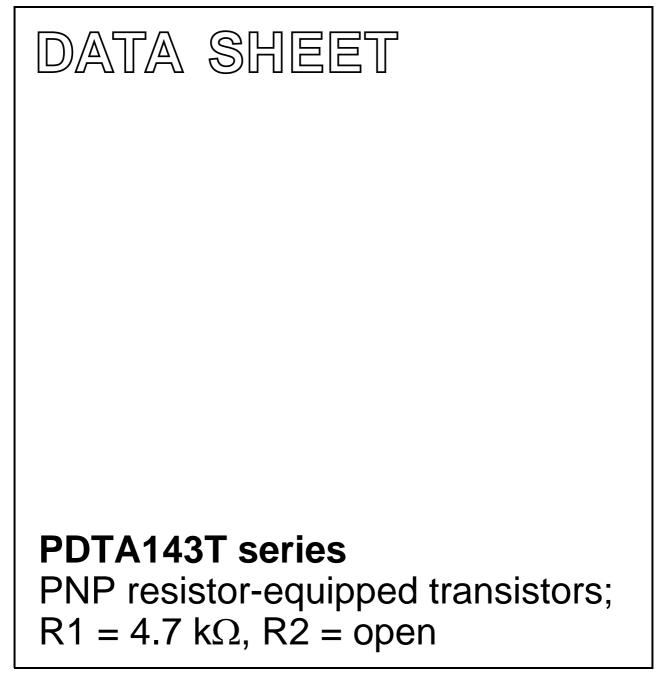
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2003 Sep 08 2004 Aug 04



PDTA143T series

FEATURES

- · Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- · General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

PRODUCT OVERVIEW

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-	-50	V
lo	output current (DC)	-	-100	mA
R1	bias resistor	4.7	-	kΩ
R2	open	-	-	-

DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

TYPE NUMBER	PACKAGE			NPN COMPLEMENT	
	PHILIPS	EIAJ	MARKING CODE		
PDTA143TE	SOT416	SC-75	39	PDTC143TE	
PDTA143TEF	SOT490	SC-89	10	PDTC143TEF	
PDTA143TK	SOT346	SC-59	45	PDTC143TK	
PDTA143TM	SOT883	SC-101	E6	PDTC143TM	
PDTA143TS	SOT54 (TO-92)	SC-43	TA143T	PDTC143TS	
PDTA143TT	SOT23	_	*42 ⁽¹⁾	PDTC143TT	
PDTA143TU	SOT323	SC-70	*45 ⁽¹⁾	PDTC143TU	

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

PNP resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

PDTA143T series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

	SIMPLIFIED OUTLINE AND SYMBOL		PINNING		
TYPE NUMBER			DESCRIPTION		
PDTA143TS		PIN 1 2 3	base collector emitter		
PDTA143TE PDTA143TEF PDTA143TK PDTA143TT PDTA143TU	3 1 3 1 2 Top view MDB272	1 2 3	base emitter collector		
PDTA143TM	2 1 Bottom view MDB266	1 2 3	base emitter collector		

PDTA143T series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	-5	V
lo	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$			
	SOT23	note 1	_	250	mW
	SOT54	note 1	_	500	mW
	SOT323	note 1	-	200	mW
	SOT346	note 1	-	250	mW
	SOT416	note 1	-	150	mW
	SOT490	notes 1 and 2	-	250	mW
	SOT883	notes 2 and 3	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air		
	SOT23	note 1	500	K/W
	SOT54	note 1	250	K/W
	SOT323	note 1	625	K/W
	SOT346	note 1	500	K/W
	SOT416	note 1	833	K/W
	SOT490	note 1	500	K/W
	SOT883	notes 2 and 3	500	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

PNP resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

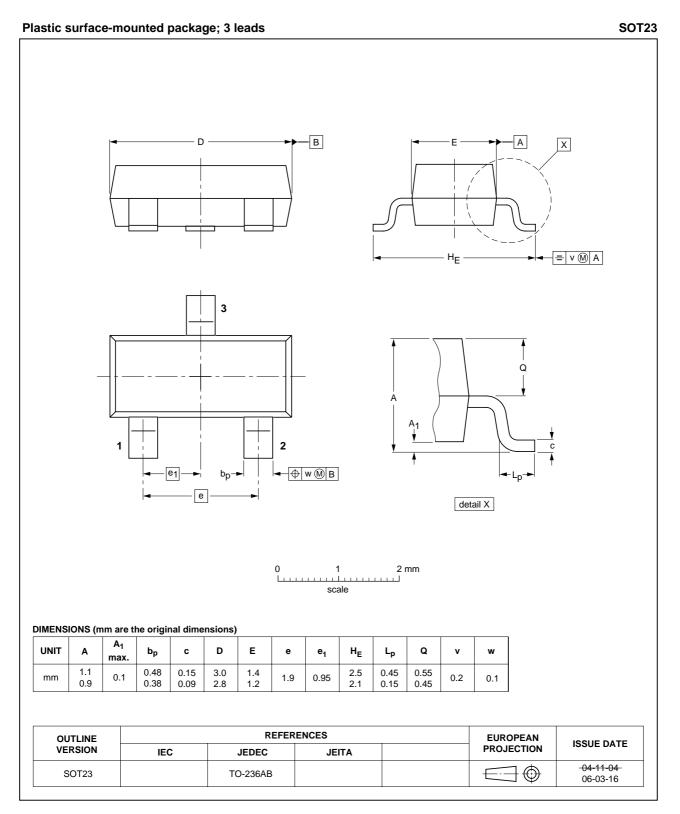
PDTA143T series

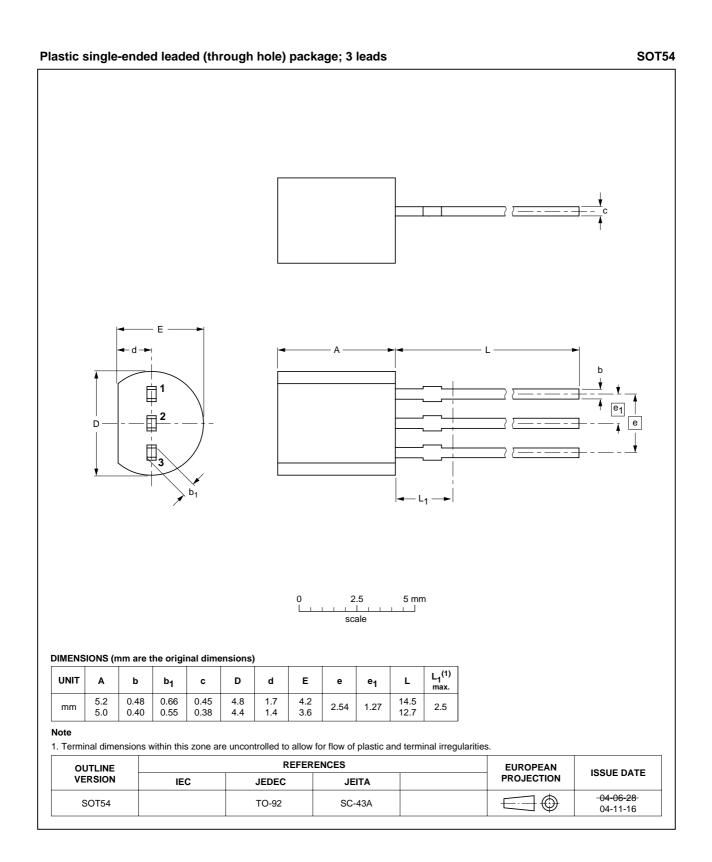
CHARACTERISTICS

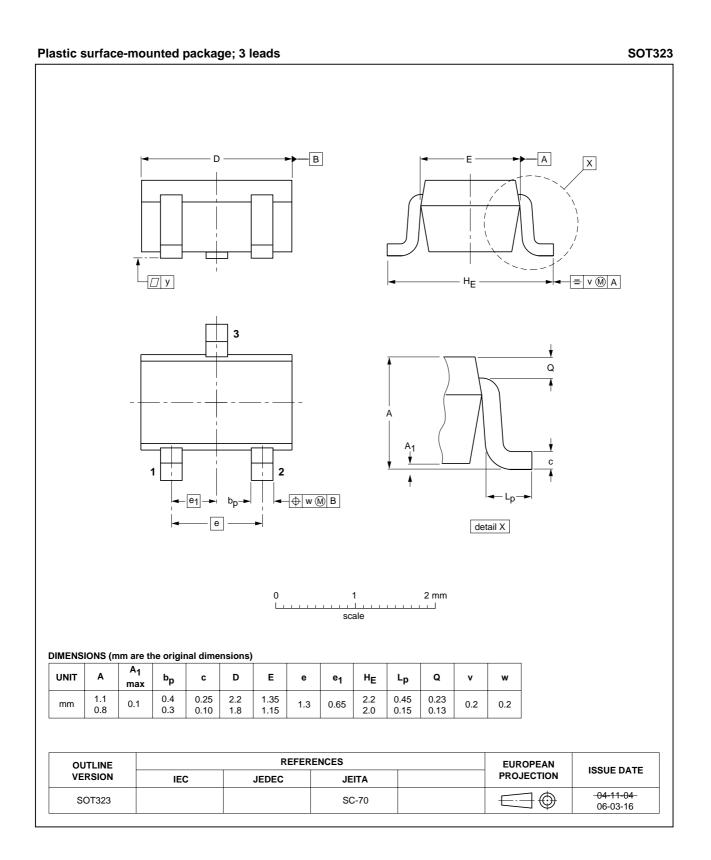
 T_{amb} = 25 °C unless otherwise specified.

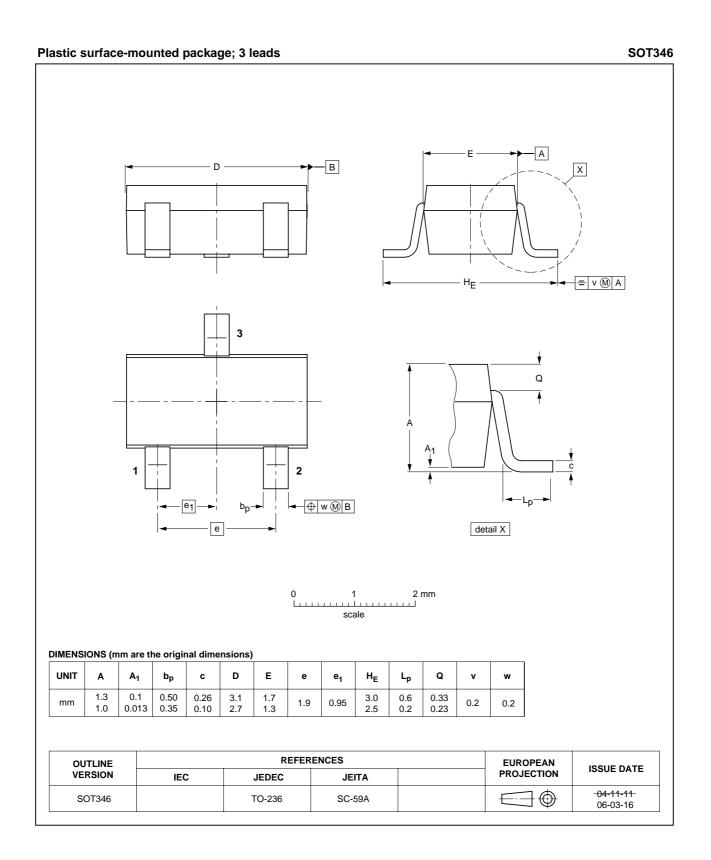
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	-	-	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	-	_	-1	μA
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 ^{\circ}\text{C}$	-	-	-50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0$	-	_	-100	nA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -1 \text{ mA}$	200	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{\rm C} = -5$ mA; $I_{\rm B} = -0.25$ mA	-	-	-150	mV
R1	input resistor		3.3	4.7	6.1	kΩ
Cc	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V; f = 1 MHz$	-	_	3	pF

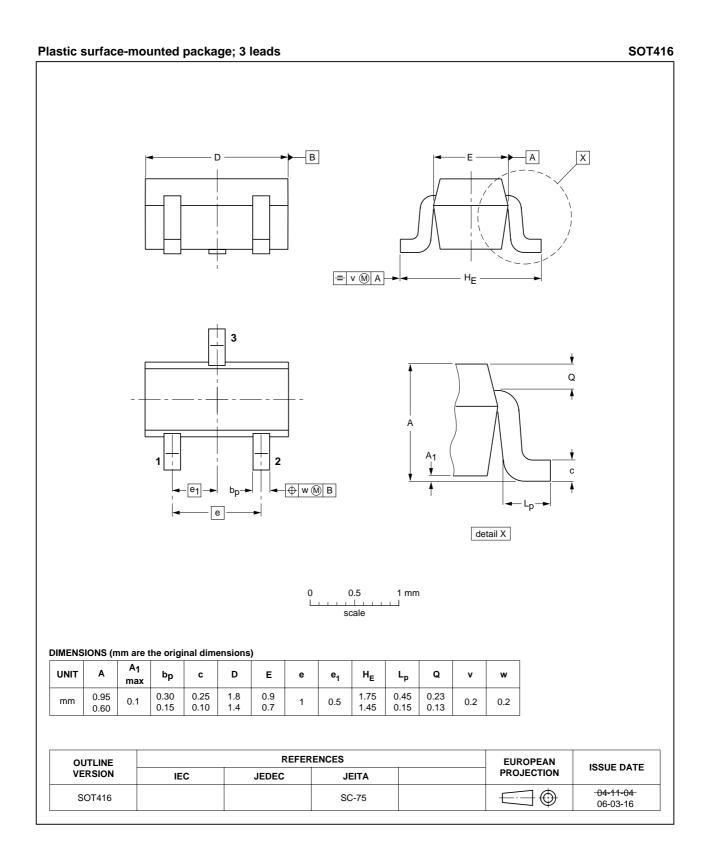
PACKAGE OUTLINES

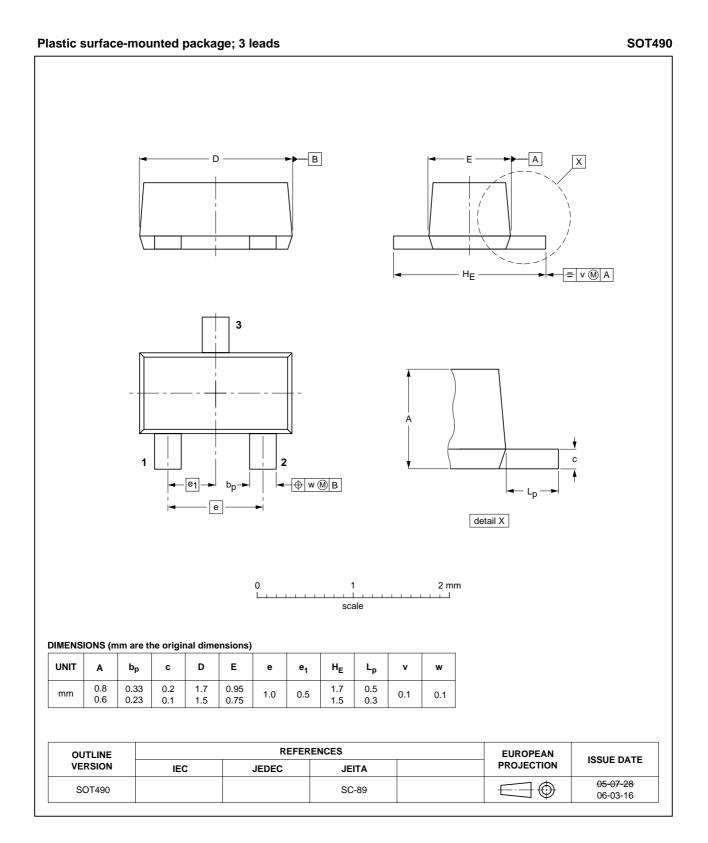


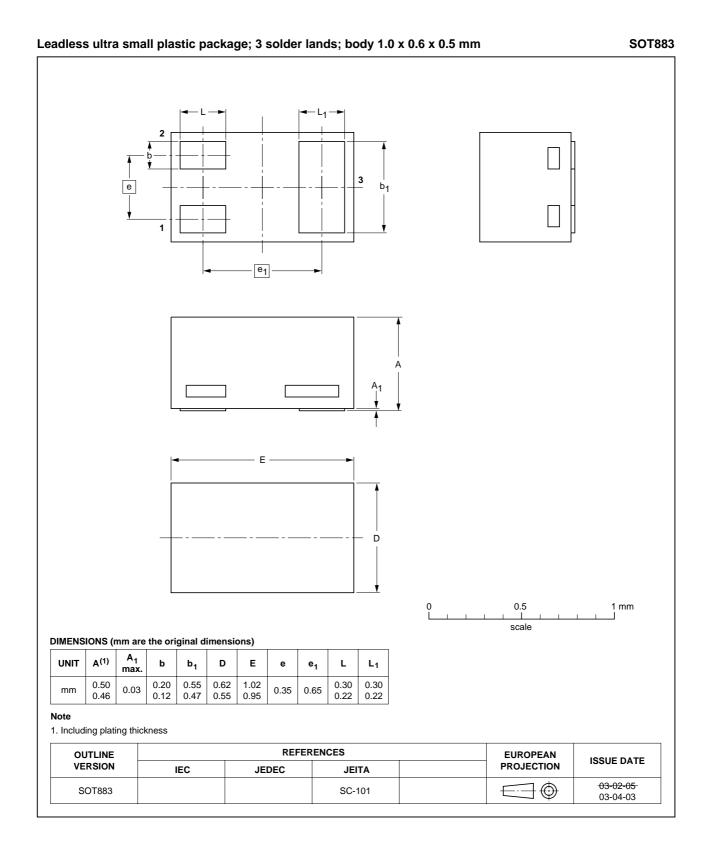












PDTA143T series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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